

## AMENDMENTS TO THE SPECIFICATION

**Please amend paragraph [0003] on pages 1-2, as follows:**

[0001] Therefore, in order to flatten a printed board in which the surface is formed in an uneven form as described above, the a-following method has been proposed. The For example, a method comprises comprising: laminating a semi-cured resin sheet onto circuit patterns; pressing the resin sheet in a reduced pressure atmosphere so as to have the resin fill in the spaces between the circuit patterns, and curing the resin; and polishing the cured resin covering the circuit patterns, in order to obtain a smoothed substrate with exposed circuit patterns.

**Please amend paragraph [0015] on page 7, as follows:**

[0002] Next, as shown in Figure 4, a pair of mirror surface plates 32 with a thickness of about 1 mm are arranged via Tedlars 31 at the outermost parts of the thirteen sets of laminated bodies 30. On the mirror surface plates 32, kraft papers 33 (e.g., with a thickness of 0.25 mm × 5 sheets) as a cushioning material, stainless jig plates 34 (e.g., with a thickness of 4 or 5 mm) and top boards 35 (e.g., with a thickness of 4 mm) as heat insulating materials, are respectively laminated in this sequence. The entire assembly of materials is placed on a carrier plate 36-so as to be covered by a cap 37. After having been thusly arranged, the assembly of materials including the carrier plate 36-and the cap 37 are then placed at a predetermined position in a pressing machine in order to be pressed at a pressure of approximately 30 kg/cm<sup>2</sup> in a reduced pressure atmosphere. As a result, the surface of the resin layers 16, which is in a gradually rising/falling state, is compressed. The resin on the circuit patterns 15 is moved so as to fill the spaces between the circuit patterns. As a result, the substrate as a whole is flattened. The air bubbles in the resin layers 16 rise up to the vicinity of the surface of the resin layers 16 so as to be removed from inside of the resin.

**Please amend paragraph [0017] on page 8, as follows:**

[0003] When the resin is completely cured, the carrier plate 36-is carried out from the pressing machine and the laminated bodies 30 are removed. The nickel foils 17 adhered to the surfaces of

the resin layers 16 of each laminated body 30 are then removed by an etching solution used exclusively for nickel (see Figures 5 and 6). As a result, the thickness of the resin layers remaining on the copper circuit patterns 15 becomes 10  $\mu\text{m}$  or less and the surface of the resin is in a roughened state. In order to flatten the substrate, primary smooth surface polishing is performed by ceramic buff polishing to remove the resin layers 16 from the circuit patterns 15. Secondary finish polishing is then performed by a surface grinding machine in order to bring the average roughness accuracy of the surface to become equal to or less than 3  $\mu\text{m}$  (see Figure 7). In the case of surface polishing, since the resin layers 16 remaining on the circuit patterns 15 have an extremely thin thickness (e.g., such as 10  $\mu\text{m}$ ) and the surface of the resin layers is roughened, the surface polishing is easily performed.

**Please amend paragraph [0023] on page 9, as follows:**

#### **INDUSTRIAL APPLICABILITY**

**[0004]** As described above, according to the present invention a flat printed wiring board with exposed circuit patterns can be manufactured with a good level of productivity.